

Green

Selection Guide

| Part No. | Dice | Lens Type | Iv (mcd) [2] @ 10mA | | Viewing Angle [1] |
|------------------|-------------|----------------|------------------------|------|----------------------|
| | | | Min. | Typ. | 2θ1/2 |
| L-7113BR-17.8/GD | Green (GaP) | Green Diffused | 15 | 30 | 30° |

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Typ. | Max. | Units | Test Conditions |
|--------|--------------------------|--------|------|------|-------|-----------------|
| λpeak | Peak Wavelength | Green | 565 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Green | 568 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Green | 30 | | nm | IF=20mA |
| C | Capacitance | Green | 15 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Green | 2.2 | 2.5 | V | IF=20mA |
| IR | Reverse Current | Green | | 10 | uA | VR = 5V |

Notes:

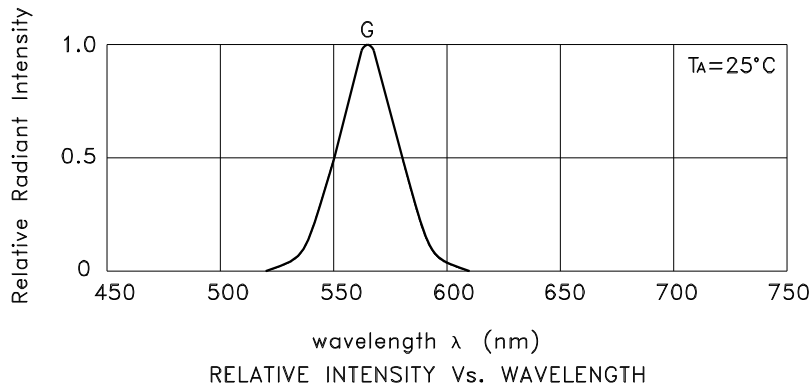
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

| Parameter | Green | Units |
|-------------------------------|---------------------|-------|
| Power dissipation | 62.5 | mW |
| DC Forward Current | 25 | mA |
| Peak Forward Current [1] | 140 | mA |
| Reverse Voltage | 5 | V |
| Operating/Storage Temperature | -40°C To +85°C | |
| Lead Solder Temperature [2] | 260°C For 3 Seconds | |
| Lead Solder Temperature [3] | 260°C For 5 Seconds | |

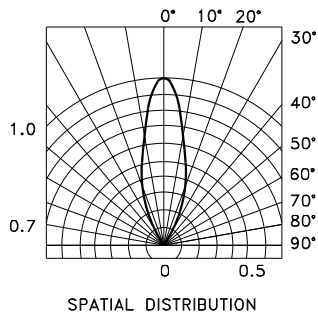
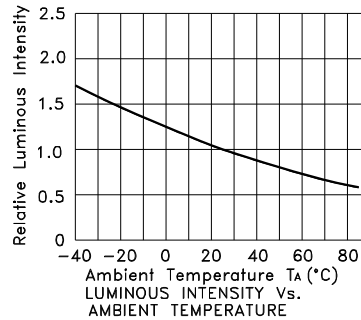
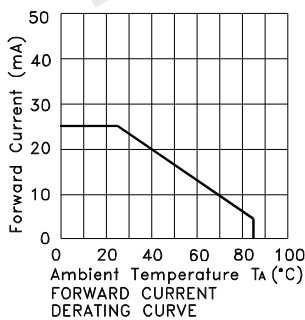
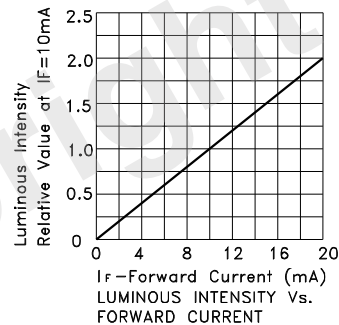
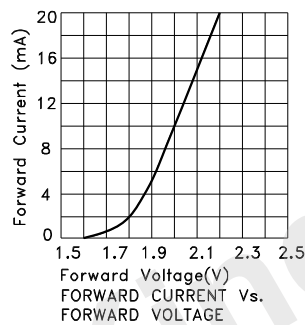
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



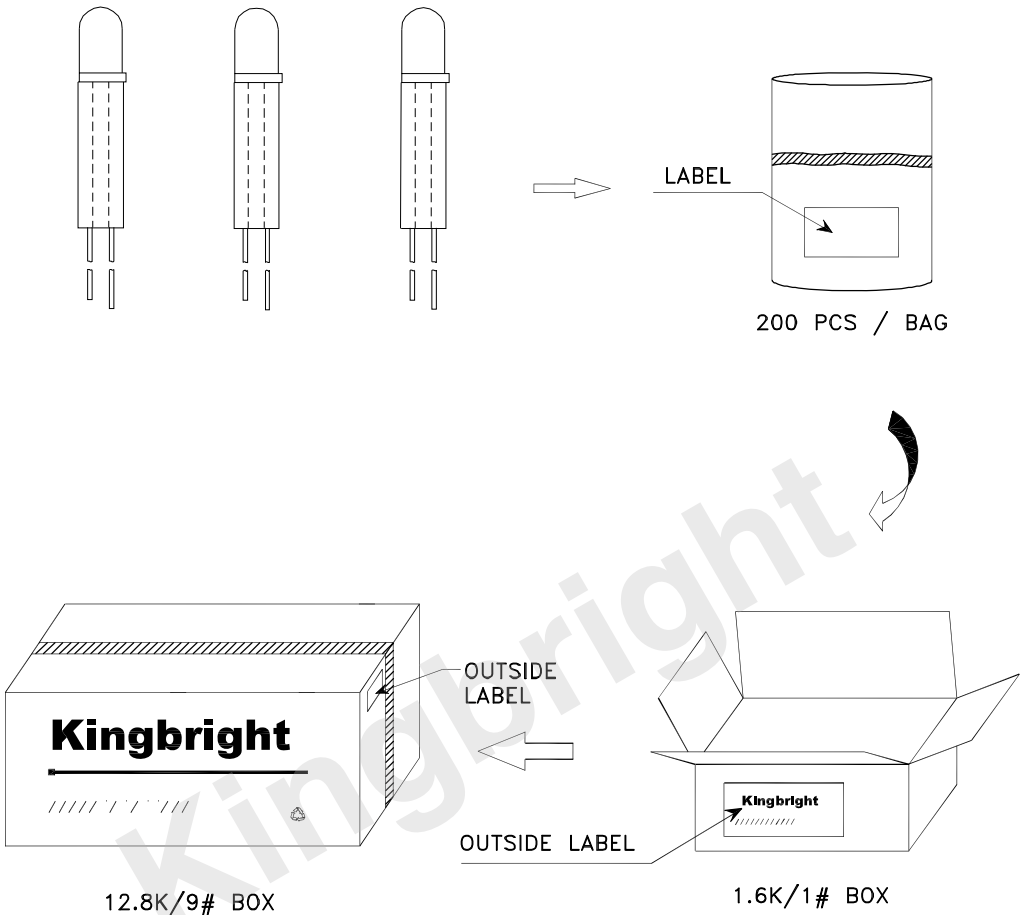
Green


L-7113BR-17.8/GD



PACKING & LABEL SPECIFICATIONS

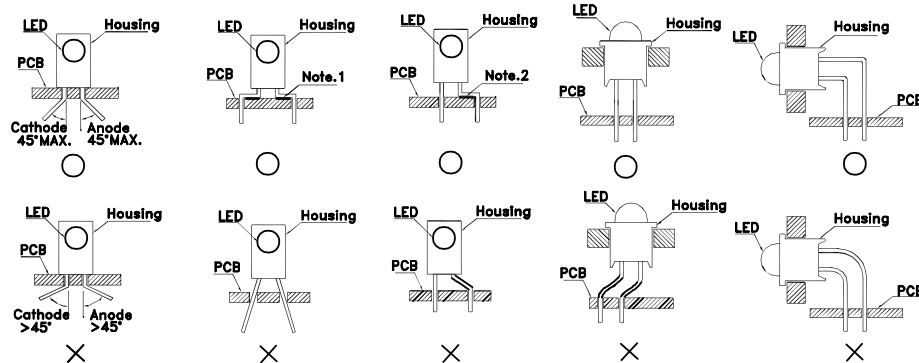
L-7113BR-17.8/GD



| | |
|--|---|
| Kingbright | |
| P/N0:L-7113BRxxx | |
| QTY: 200 pcs | Q.C. <div>Q C XX XX XXXX PASSED</div> |
| S/N: XXXX | |
| CODE: XXX | |
| LOT NO: | |
|  | |
| XXXXXXXXXXXXXXXXXXXX | |
| RoHS Compliant | |

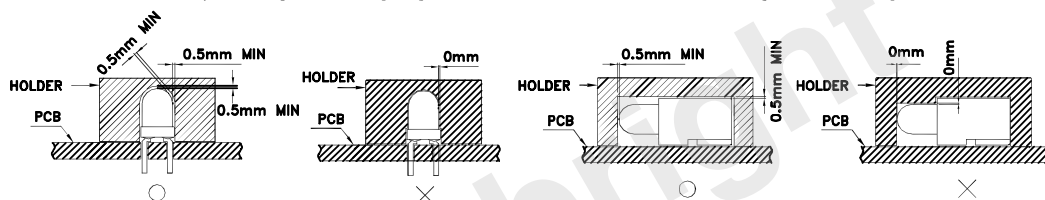
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

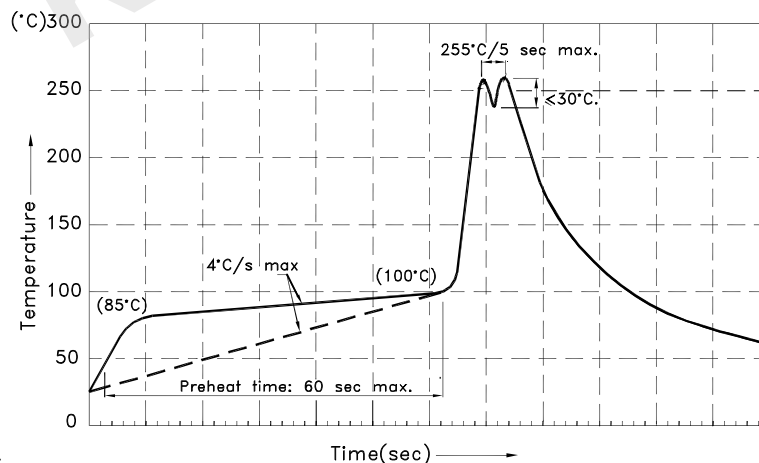


”○” Correct mounting method ”×” Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



3. The tip of the soldering iron should never touch the lens epoxy.
4. Through-hole LEDs are incompatible with reflow soldering.
5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
6. Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

Detailed application notes are listed on our website.

http://www.kingbright.com/application_notes